

EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on May 13, 2020)

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ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD) 25.000MHz ± 25 ppm over -40°C to +85°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	25.000MHz
Frequency Tolerance/Stability	± 25 ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	5mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH= -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL= +4mA)
Rise/Fall Time	4nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 ± 5 (%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	80% of Vdd Minimum or No Connect to Enable Output, 20% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10 μ A Maximum (Disabled Output: High Impedance)
RMS Phase Jitter	1pSec Maximum (Fj = 12kHz to 20MHz)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	E25.0 E=Ecliptek Designator
2	XXXXX XXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)
Test Circuit for CMOS Output


Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

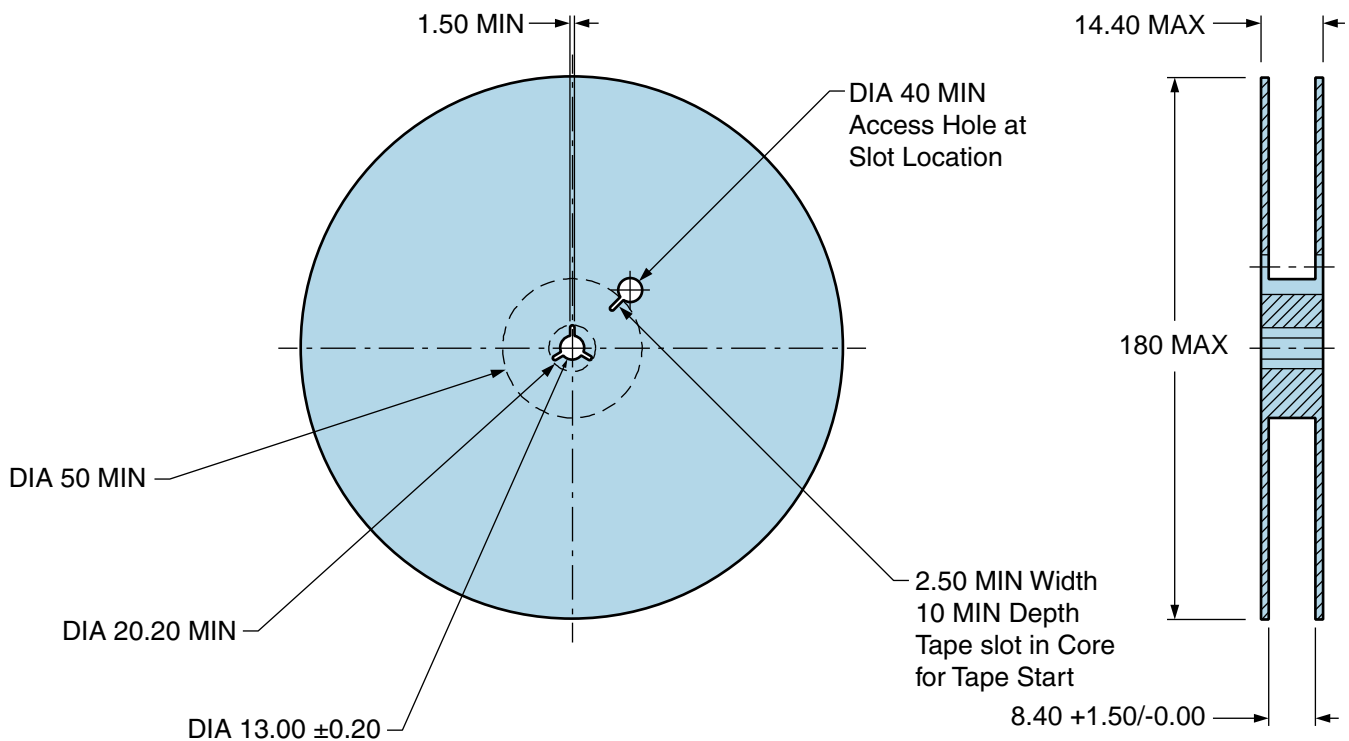
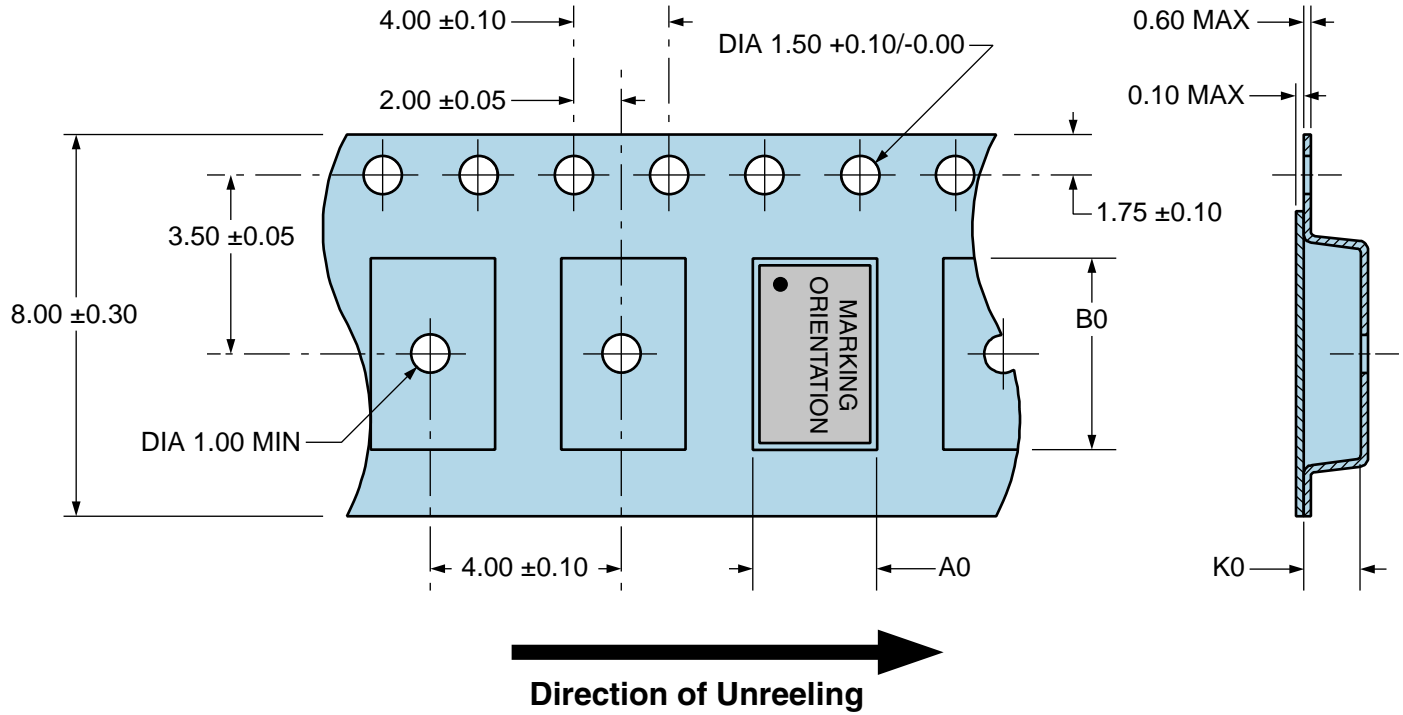
EB13E2J2H-25.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)
Recommended Solder Reflow Methods

High Temperature Infrared/Convection

T_S MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
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Preheat

- Temperature Minimum (T_S MIN)	150°C
- Temperature Typical (T_S TYP)	175°C
- Temperature Maximum (T_S MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds

Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
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Time Maintained Above:

- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds

Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (T_P Target)	250°C +0/-5°C
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Time within 5°C of actual peak (t_p)	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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EB13E2J2H-25.000M TR [Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to Tl (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (Tl to Tp)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (Tl)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (Tp)	240°C Maximum
Target Peak Temperature (Tp Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.